



115V N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{DSS}	BV _{DSS} @T _{Jmax}	R _{DS(ON)} Max	I _D Max T _A = +25°C
		90mΩ @ V _{GS} = 10V	3.4A
115V	120V	100mΩ @ V _{GS} = 4.5V	2.3A

Features and Benefits

- 0.4mm Profile—Ideal for Low Profile Applications
- PCB Footprint of 4mm²
- 100% Unclamped Inductive Switching (UIS) Test in Production— Ensures More Reliable and Robust End Application
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please <u>contact us</u> or your local Diodes representative. https://www.diodes.com/quality/product-definitions/

Description

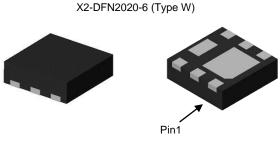
This new generation MOSFET is designed to minimize the on-state resistance ($R_{DS(ON)}$) yet maintain superior switching performance, which makes it ideal for high-efficiency power management applications.

Applications

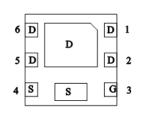
- DC-DC Primary Switch
- Load Switch

Mechanical Data

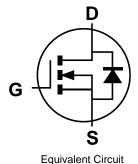
- Case: X2-DFN2020-6
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish—NiPdAu over Copper Leadframe.
 Solderable per MIL-STD-202, Method 208 (4)
- Weight: 0.006 grams (Approximate)







Pin Out Bottom View



Ordering Information (Note 4)

Part Number	Case	Quantity Per Reel
DMT12H090LFDF4-7	X2-DFN2020-6 (Type W)	3,000
DMT12H090LFDF4-13	X2-DFN2020-6 (Type W)	10,000

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.



Marking Information

Site 1:



X4 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: I = 2021) M = Month (ex: 9 = September)

Date Code Key

Year	2018		2021	2022	2023	2024	2025	2026	2027	2028	2029	2030
Code	F		l	J	K	L	М	N	0	Р	R	S
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec

Site 2:



X4 = Product Type Marking Code YWX = Date Code Marking Y = Year (ex: 1 = 2021) W = Week (ex: a = Week 27; z Represents Week 52 and 53) X = Internal Code (ex: U = Monday)

Date Code Key

Year	2018	 2021	2022	2023	2024	2025	2026	2027	2028	2029	2030
Code	8	 1	2	3	4	5	6	7	8	9	0

Week	1-26	27-52	53
Code	A-Z	a-z	z

Internal Code	Sun	Mon	Tue	Wed	Thu	Fri	Sat
Code	T	U	V	W	X	Y	Z



Maximum Ratings (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Drain-Source Voltage		VDSS	115	V
Gate-Source Voltage		V_{GSS}	±12	V
Continuous Drain Current, V _{GS} = 10V (Note 6)	lo	3.4 2.7	А	
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)		I _{DM}	15	Α
Maximum Body Diode Continuous Current (Note 6)		Is	3.4	Α
Pulsed Body Diode Continuous Current (10µs Pulse, Duty Cycle = 1	Ism	15	Α	
Avalanche Current, L = 0.3mH	las	2.3	Α	
Avalanche Energy, L = 0.3mH		Eas	0.79	mJ

Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit	
Total Dower Dissipation (Note 5)	T _A = +25°C	D-	0.9	١٨/	
Total Power Dissipation (Note 5)	T _A = +70°C	PD	0.6	W	
Thermal Resistance, Junction to Ambient (Note 5)	·	Rөja	141	°C/W	
Total Davies Dissipation (Note C)	T _A = +25°C	T _A = +25°C		14/	
Total Power Dissipation (Note 6)	T _A = +70°C	PD	1.0	W	
Thermal Resistance, Junction to Ambient (Note 6)	·	R _{OJA}	78	2011	
Thermal Resistance, Junction to Case (Note 6)	Rejc	15	°C/W		
Operating and Storage Temperature Range		T _{J,} T _{STG}	-55 to +150	°C	

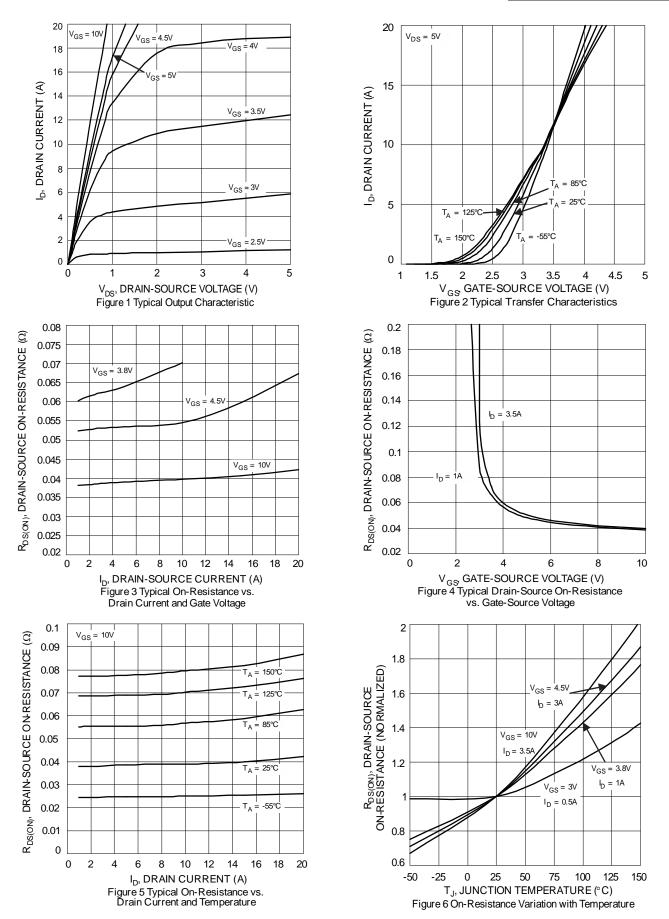
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV _{DSS}	115	_	_	V	$V_{GS} = 0V$, $I_D = 10mA$
Zero Gate Voltage Drain Current	IDSS	_	_	1	μΑ	V _{DS} = 92V, V _{GS} = 0V
Gate-Source Leakage	Igss	_	_	±100	nA	$V_{GS} = \pm 9.6V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	VGS(TH)	0.6		2.2	V	$V_{DS} = V_{GS}$, $I_D = 250\mu A$
		_	_	90		Vgs = 10V, ID = 3.5A
Static Drain-Source On-Resistance		_		100	mΩ	Vgs = 4.5V, ID = 3.0A
Static Drain-Source On-Resistance	RDS(ON)	_	_	300	11122	V _G S = 3.8V, I _D = 1.0A
		_	_	350		$V_{GS} = 3V, I_D = 0.5A$
Diode Forward Voltage	VsD	_	_	1.3	V	V _G S = 0V, I _S = 2.4A
DYNAMIC CHARACTERISTICS (Note 8)						•
Input Capacitance	Ciss	_	251	_	pF	., 50,4,74, 0,4
Output Capacitance	Coss	_	80	_	pF	$V_{DS} = 50V, V_{GS} = 0V,$ - f = 1MHz
Reverse Transfer Capacitance	Crss	_	3	_	pF	1 = 1101112
Gate Resistance	Rg	_	7	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$
Total Gate Charge	Qg	_	6	_	nC	
Gate-Source Charge	Qgs	_	0.3	_	nC	$V_{DS} = 50V, I_{D} = 4.5A,$
Gate-Drain Charge	Qgd	_	2	_	nC	Vgs = 10V
Turn-On Delay Time	t _{D(ON)}	_	2.2	_	ns	
Turn-On Rise Time	t _R	_	2.6	_	ns	$V_{DS} = 50V, R_L = 11\Omega$
Turn-Off Delay Time	tD(OFF)	_	9.3	_	ns	$V_{GS} = 10V$, $R_{GEN} = 3\Omega$
Turn-Off Fall Time	tF	_	3.9	_	ns	7
Reverse Recovery Time	trr	_	83	_	ns	1 4 5 4 31/34 000 4/3
Reverse Recovery Charge	Q _{RR}	_	189	_	nC	I _F = 4.5A, di/dt = 300A/μs

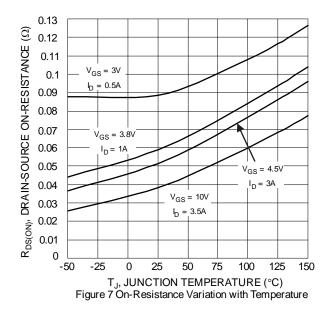
Notes:

- 5. Device mounted on FR-4 substrate PCB, 2oz copper, with minimum recommended pad layout.
- 6. Device mounted on FR-4 substrate PCB, 2oz copper, with 1inch square copper plate.
- 7. Short duration pulse test used to minimize self-heating effect.
- 8. Guaranteed by design. Not subject to product testing.









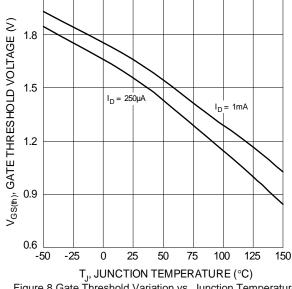
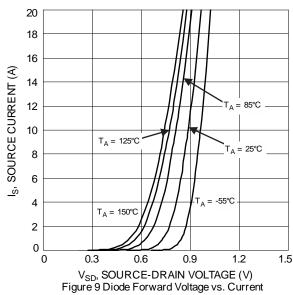
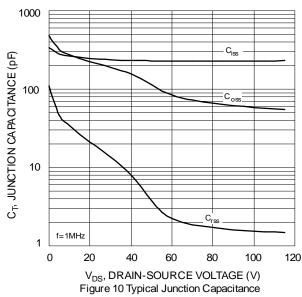
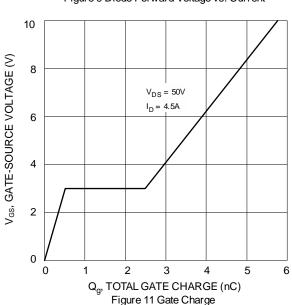
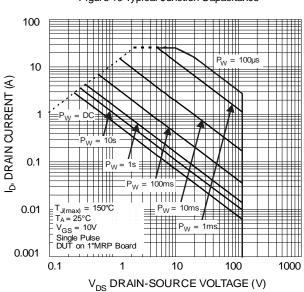


Figure 8 Gate Threshold Variation vs. Junction Temperature









March 2021

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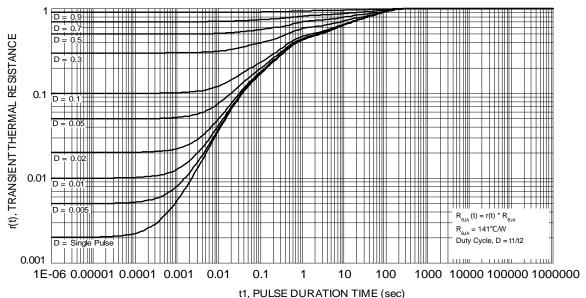


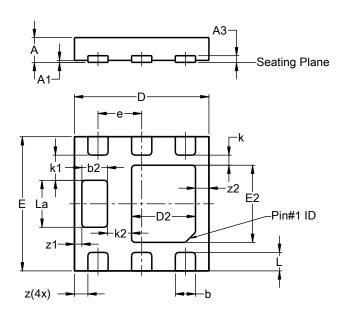
Figure 13 Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

X2-DFN2020-6 (Type W)

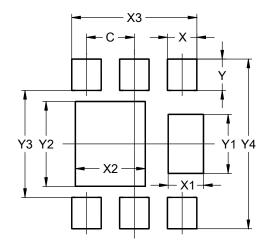


	X2-DFN2020-6 Type W							
Dim	Min	Тур						
Α	0.34	0.40	0.37					
A1	0.00	0.05	0.02					
A3	_		0.100					
b	0.25	0.35	0.30					
b2	0.33	0.43	0.38					
D	1.95	2.05	2.00					
D2	0.85	1.05	0.95					
Е	1.95	2.05	2.00					
E2	1.05	1.25	1.15					
е	_							
k	_		0.15					
k1	_		0.375					
k2	_		0.36					
L	0.225	0.325	0.275					
La	0.65	0.75	0.70					
Z	_		0.20					
z1			0.11					
z2			0.20					
All	Dimensi	ions in r	nm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

X2-DFN2020-6 (Type W)



Dimensions	Value
פווטופוופוווט	(in mm)
С	0.650
X	0.400
X1	0.480
X2	0.950
Х3	1.700
Y	0.425
Y1	0.800
Y2	1.150
Y3	1.450
Y4	2.300

March 2021

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